### **N-Channel Enhancement Mode Power MOSFET**

Drain-Source Voltage: 800V Continuous Drain Current: 8A

#### DESCRIPTION

The ATM8N80TF is a N-channel mode power MOSFET, it uses ATs advanced technology to provide costumers planar stripe and DMOS technology. This technology allows a minimum on-state resistance, superior switching performance. It also can withstand high energy pulse in the avalanche and commutation mode.

The ATM8N80TF is generally applied in high efficiency switch mode power supplies.

#### **FEATURES**

- Typically 35 nC Low Gate Charge
- $R_{DS(ON)} < 1.45\Omega @ V_{GS} = 10V, I_D = 4.0A$
- Typically 13 pF Low C<sub>RSS</sub>
- Improved dv/dt Capability
- Fast Switching Speed
- ♦ 100% Avalanche Tested
- RoHS–Compliant Product

#### ABSOLUTE MAXIMUM RATINGS (Tc=25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V <sub>DSS</sub>	800	V
Gate-Source Voltage		V <sub>GSS</sub>	±30	V
Drain Current (Continuou <mark>s) (T</mark> c=25°C)		ID	8	A
Drain Current (Pulsed) (Note1)		I <sub>DM</sub>	32	А
Avalanche Current (Note 1)		I <sub>AR</sub>	8	А
Single Pulse Avalanche Energy (Note 3)		E <sub>AS</sub>	850	mJ
Repetitive Avalanche Energy (Note 1)		E <sub>AR</sub>	17.8	mJ
Peak Dio <mark>de</mark> Recovery dv/dt (Note 4)		dv/dt	4.5	V/ns
Power Dissipation	TO-220F		59	W
Linear Derating Factor above (Tc=25°C)	TO-220F	PD	0.47	W/°C
Junction Temperature		TJ	+150	°C
Storage Temperature		T <sub>STG</sub>	-55 ~ +150	°C

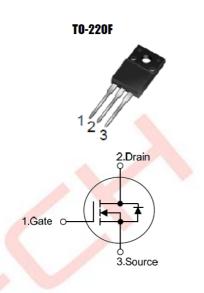
Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3. L = 25mH, I\_{AS} = 8A, V\_DD = 50V, R\_G = 25  $\Omega,$  Starting T\_J = 25°C
- 4.  $I_{SD} \le 8A$ , di/dt  $\le 200A/\mu s$ ,  $V_{DD} \le BV_{DSS}$ , Starting  $T_J = 25^{\circ}C$



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### ELECTRICAL CHARACTERISTICS (Tc=25°C, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V	800			V
Breakdown Voltage Temperature Coefficient	∆BV <sub>DSS</sub> /∆T <sub>J</sub>	Reference to 25°C, I⊳=250µA		0.5		V/°C
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =800V, V <sub>GS</sub> =0V V <sub>DS</sub> =640V, T <sub>C</sub> =125°C			10 100	μA
Gate- Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V			±100	nA
ON CHARACTERISTICS		· · · · · · · · · · · · · · · · · · ·	1			
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250µA	3.0		5.0	V
Static Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =4A		1.18	1.45	Ω
Forward Transconductance (Note 1)	<b>G</b> FS	V <sub>DS</sub> =50V, I <sub>D</sub> =4A		5.6	1	S
DYNAMIC PARAMETERS					10	
Input Capacitance	CISS			1580	2050	pF
Output Capacitance	Coss	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V, f=1.0MHz	5	135	175	pF
Reverse Transfer Capacitance	C <sub>RSS</sub>			13	17	pF
SWITCHING PARAMETERS (Note 1, Note	e 2)					
Total Gate Charge	$Q_{G}$			47	60	nC
Gate to Source Charge	Q <sub>GS</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =400V, I <mark>D</mark> =8A R∟=50Ω		10		nC
Gate to Drain Charge	Q <sub>GD</sub>	112-3022		14		nC
Turn-ON Delay Time	t <sub>D(ON)</sub>			40	90	ns
Rise Time	t <sub>R</sub>	Vpp=400V, Ip=8A, Rg=25Ω		110	230	ns
Turn-OFF Delay Time	$t_{D(OFF)}$	VDD=400V, ID=6A, RG-2502		65	140	ns
Fall-Time	t⊨			70	150	ns
SOURCE- DRAIN DIODE RATINGS AND C	HARACTERIS	TICS		-		
Maximum Continuous Drain-Source Diode Forward Current	Is				8	А
Maximum Pulsed Drain-Source Diode	I <sub>SM</sub>				32	A
Drain-Source Diode Forward Voltage	V <sub>SD</sub>	Is=8A, V <sub>GS</sub> =0V			1.4	V
Reverse Recovery Time (Note 1)	t <sub>rr</sub>	Is=8A, V <sub>GS</sub> =0V,		690		ns
Reverse Recovery Charge (Note 1)	Q <sub>RR</sub>	dl⊧/dt=100A/µs		8.2		μC

Note: 1. Pulse Test: Pulse width  $\leq$  300µs, Duty cycle  $\leq$  2%

2. Essentially independent of operating temperature

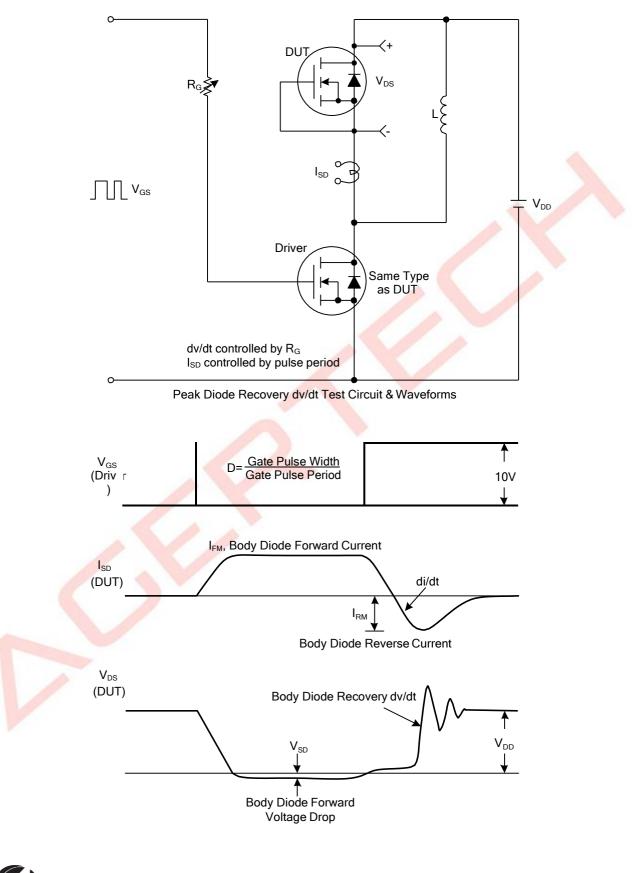


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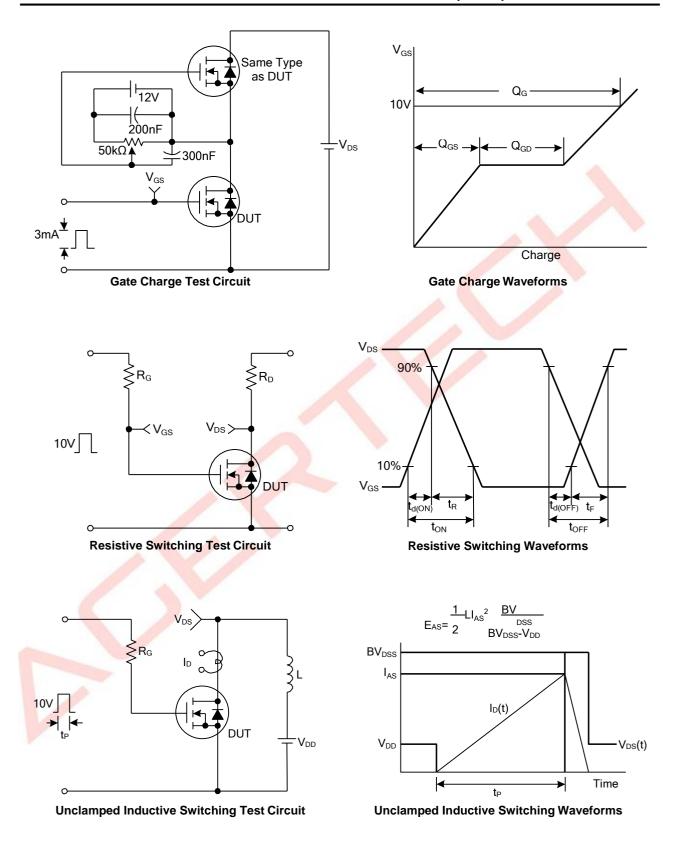
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### <u>ATM8N80TF</u>

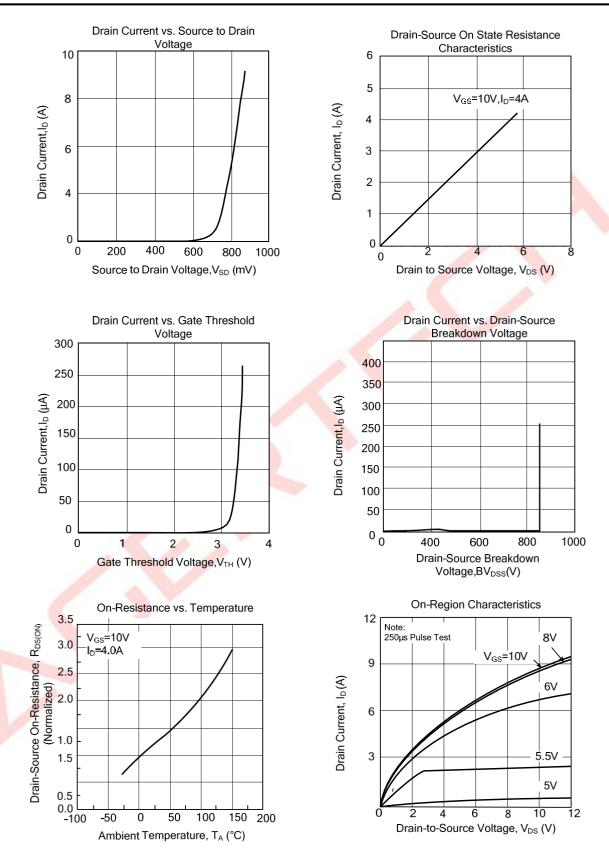
#### **TEST CIRCUITS AND WAVEFORMS(Cont.)**





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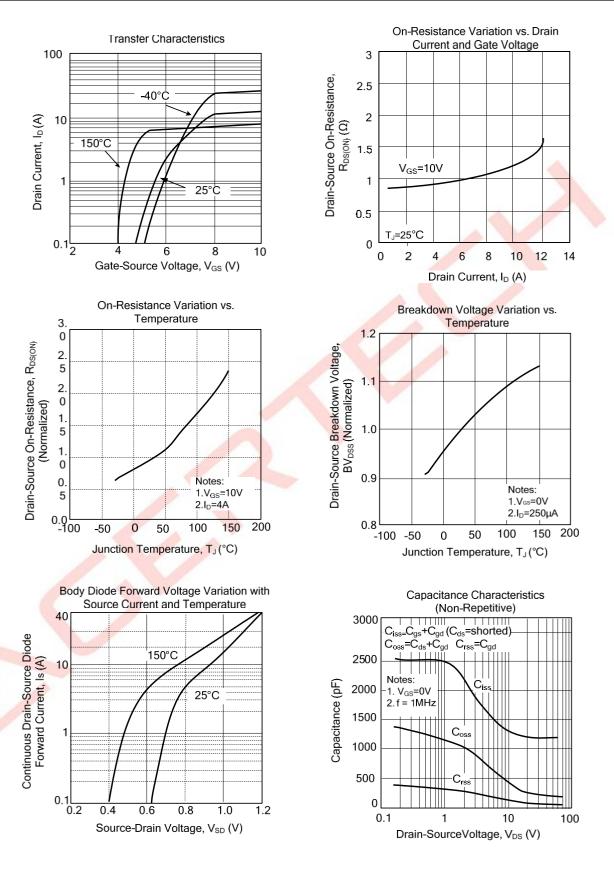


#### **TYPICAL CHARACTERISTICS CURVES**



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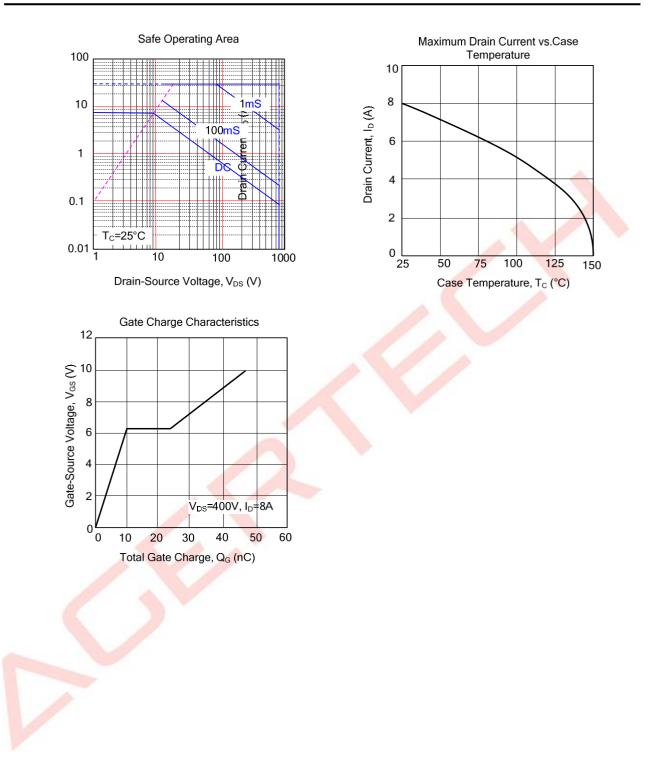
#### **TYPICAL CHARACTERISTICS CURVES (Cont.)**



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#### **TYPICAL CHARACTERISTICS CURVES (Cont.)**



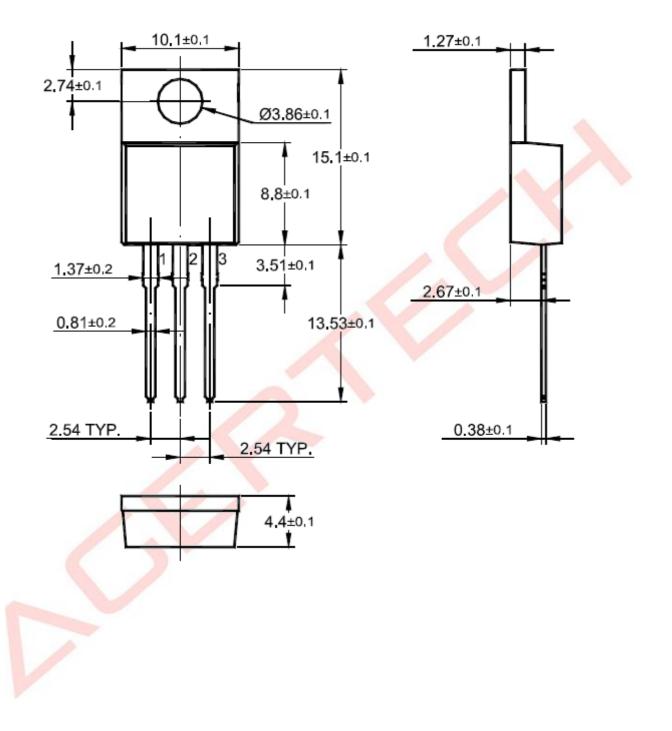


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Package Outline

#### TO-220F





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